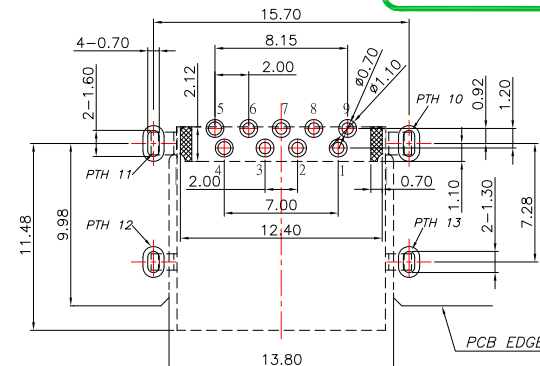
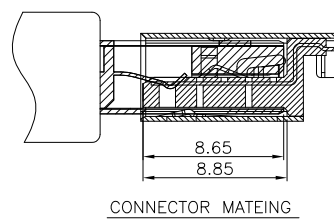
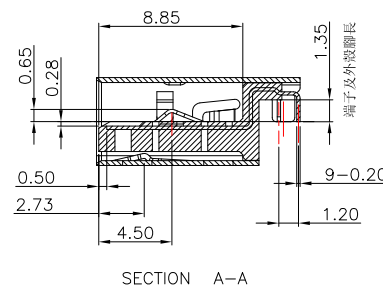
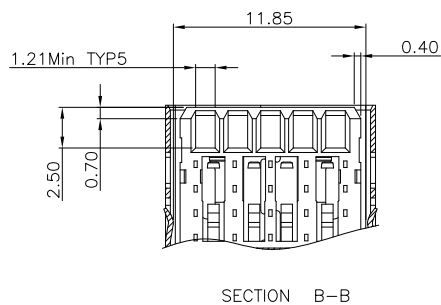
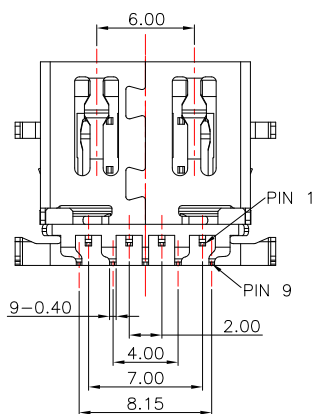
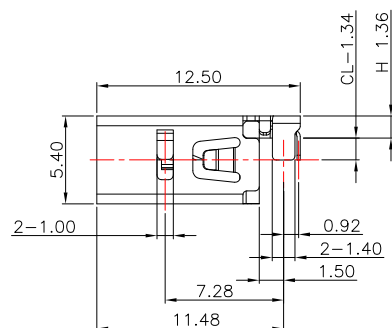
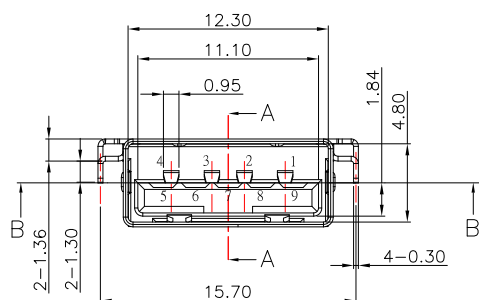
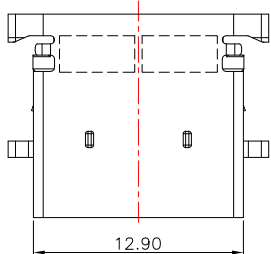




SUA-110E7-30xx-S277

鍍層厚度: HOUSING:

Blank : 1u"	Blank : Blue
2 : 15u"	K : BLack
3 : 30u"	



RECOMMENDED PCB LAYOUT TOP VIEW

NOTE:

1.MATERIAL:

- 1.1 Housing: High Temperature Plastic,
- 1.2 Contact: Copper Alloy
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Rate: 30V DC , 1.5 A
- 3.2 Insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



东莞市高迪电子有限公司
Dong Guan KDRR Electronic Switch Jack Co., Ltd.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 06/15/17
DATE: 06/15/17
DATE: 06/15/17

MAT'L
FINISH
SCALE: 1 : 1
SHEET NO. 1 of 1

TITLE: CONNECTOR
MODLE: USB AF 3.0 DIP 沉板, 板上H:1.36mm L:12.5, 無捲邊反向
DWG NO. SUA-110E7-30xx-S277
PART NO. SUA-110E7-30xx-S277

SIZE: A4
VER: R

ITEM NO.	DESCRIPTION	DRAWN	DATE